

Variant: 001
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 TID #: TIDA-01478



TIDA-01478 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-01478	Any	Printed Circuit Board	
2	C1	1	1uF	C1608X5R1H105K080AB	TDK	CAP, CERM, 1 μ F, 50 V, +/- 10%, X5R, 0603	0603
3	C2	1	22uF	GRM21BZ71A226ME15L	MuRata	CAP, CERM, 22 μ F, 10 V, +/- 20%, X7R, 0805	0805
4	C3	1	0.047uF	C1005X7R1H473K050BB	TDK	CAP, CERM, 0.047 μ F, 50 V, +/- 10%, X7R, 0402	0402
5	C4, C7	2	1uF	C1005JB1V105K050BC	TDK	CAP, CERM, 1 μ F, 35 V, +/- 10%, JB, 0402	0402
6	C5, C6	2	0.1uF	C1608X5R1H104K080AA	TDK	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X5R, 0603	0603
7	D1	1	200V	RF071M2S	Rohm	Diode, Ultrafast, 200 V, 1 A, SOD-123	SOD-123
8	D2, D3, D4	3	30V	SMAJ30CA	Littelfuse	Diode, TVS, Bi, 30 V, SMA	SMA
9	J1	1		09 0431 212 04	Binder-Connector	M12 Socket, 4Pos, TH	M12 Conn D12x14.3
10	J2	1		TSW-105-07-F-D	Samtec	Header, 2.54mm, 5x2, Gold, Black, TH	Header, 2.54mm, 5x2, TH
11	L1	1	47uH	XPL2010-473MLB	Coilcraft	Inductor, Shielded, Composite, 47 μ H, 0.25 A, 3.96 ohm, AEC-Q200 Grade 1, SMD	XPL2010
12	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
13	R1, R3, R5	3	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
14	R6, R7, R8	3	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
15	U1	1		LM5165XDRCR	Texas Instruments	3V-65V, 150mA Synchronous Buck Converter With Ultra-Low IQ, DRC0010J (VSON-10)	DRC0010J
16	U2	1		TIOL111	Texas Instruments	IO-Link Device Transceiver with Integrated Surge Protection, TIOL111 (WSON-10)	TIOL111
17	U3	1		TIOS101DMWR	Texas Instruments	Digital Sensor Output Driver with Integrated Surge Protection, DMW0010A (VSON-10)	DMW0010A
18	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
19	R2, R4	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402

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